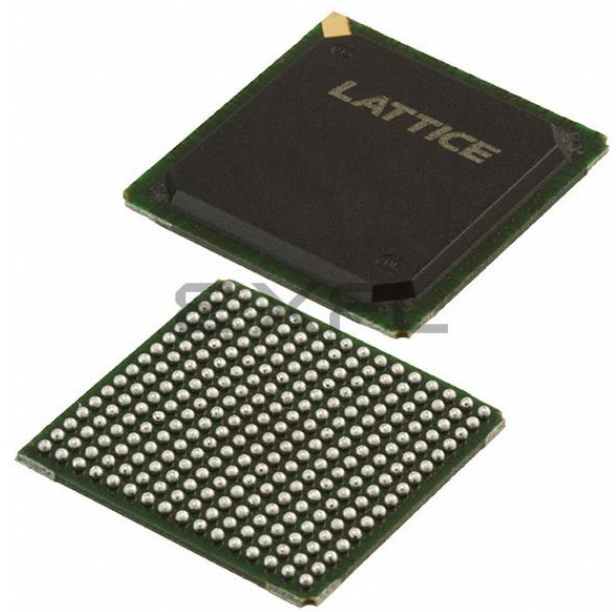
Lattice Semiconductor Corporation - LC5768MV-75FN256I Datasheet



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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	24
Number of Macrocells	768
Number of Gates	-
Number of I/O	193
Operating Temperature	-40°C ~ 105°C (TJ)
Mounting Type	Surface Mount
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lc5768mv-75fn256i

Product Line	Ordering Part Number	Product Status	Reference PCN
LC5512MV	LC5512MV-45Q208C	Active / Orderable	
	LC5512MV-45QN208C		
	LC5512MV-75Q208C		
	LC5512MV-75QN208C		
	LC5512MV-75Q208I		
	LC5512MV-75QN208I		
	LC5512MV-45F256C		
	LC5512MV-45FN256C		
	LC5512MV-75F256C		
	LC5512MV-75FN256C		
	LC5512MV-75F256I		
	LC5512MV-75FN256I		
	LC5512MV-45F484C		
	LC5512MV-45FN484C		
	LC5512MV-75F484C		
	LC5512MV-75FN484C		
	LC5512MV-75F484I		
	LC5512MV-75FN484I		
LC5512MB	LC5512MB-45Q208C	**Discontinued**	PCN#09-10
	LC5512MB-45QN208C		
	LC5512MB-75Q208C		
	LC5512MB-75QN208C		
	LC5512MB-75Q208I		
	LC5512MB-75QN208I		
	LC5512MB-45F256C	Active / Orderable	
	LC5512MB-45FN256C		
	LC5512MB-75F256C		
	LC5512MB-75FN256C		
	LC5512MB-75F256I		
	LC5512MB-75FN256I		
	LC5512MB-45F484C	**Discontinued**	PCN#09-10
	LC5512MB-45FN484C		
	LC5512MB-75F484C		
	LC5512MB-75FN484C		
	LC5512MB-75F484I		
	LC5512MB-75FN484I		
LC5512MC	LC5512MC-45Q208C	**Discontinued**	PCN#09-10
	LC5512MC-45QN208C		
	LC5512MC-75Q208C		
	LC5512MC-75QN208C		
	LC5512MC-75Q208I		
	LC5512MC-75QN208I		
	LC5512MC-45F256C		
	LC5512MC-45FN256C		
	LC5512MC-75F256C		
	LC5512MC-75FN256C		
	LC5512MC-75F256I		
	LC5512MC-75FN256I		

ispXPLD™ 5000MX Family

3.3V, 2.5V and 1.8V In-System Programmable
eXpanded Programmable Logic Device XPLD™ Family

February 2010 **Data Sheet**

Features

- **Flexible Multi-Function Block (MFB) Architecture**
  - SuperWIDE™ logic (up to 136 inputs)
  - Arithmetic capability
  - Single- or Dual-port SRAM
  - FIFO
  - Ternary CAM
- **sysCLOCK™ PLL Timing Control**
  - Multiply and divide between 1 and 32
  - Clock shifting capability
  - External feedback capability
- **sysIO™ Interfaces**
  - LVCMOS 1.8, 2.5, 3.3V
    - Programmable impedance
    - Hot-socketing
    - Flexible bus-maintenance (Pull-up, pull-down, bus-keeper, or none)
    - Open drain operation
  - SSTL 2, 3 (I & II)
  - HSTL (I, III, IV)
  - PCI 3.3
  - GTL+
  - LVDS
  - LVPECL
  - LVTTL
- **Expanded In-System Programmability (ispXP™)**
  - Instant-on capability
  - Single chip convenience
  - In-System Programmable via IEEE 1532 Interface
  - Infinitely reconfigurable via IEEE 1532 or sysCONFIG™ microprocessor interface
  - Design security
- **High Speed Operation**
  - 4.0ns pin-to-pin delays, 300MHz f_{MAX}
  - Deterministic timing
- **Low Power Consumption**
  - Typical static power: 20 to 50mA (1.8V), 30 to 60mA (2.5/3.3V)
  - 1.8V core for low dynamic power
- **Easy System Integration**
  - 3.3V (5000MV), 2.5V (5000MB) and 1.8V (5000MC) power supply operation
  - 5V tolerant I/O for LVCMOS 3.3 and LVTTL interfaces
  - IEEE 1149.1 interface for boundary scan testing
  - sysIO quick configuration
  - Density migration
  - Multiple density and package options
  - PQFP and fine pitch BGA packaging
  - Lead-free package options

Table 1. ispXPLD 5000MX Family Selection Guide

	ispXPLD 5256MX	ispXPLD 5512MX	ispXPLD 5768MX	ispXPLD 51024MX
Macrocells	256	512	768	1,024
Multi-Function Blocks	8	16	24	32
Maximum RAM Bits	128K	256K	384K	512K
Maximum CAM Bits	48K	96K	144K	192K
sysCLOCK PLLs	2	2	2	2
t_{PD} (Propagation Delay)	4.0ns	4.5ns	5.0ns	5.2ns
t_S (Register Set-up Time)	2.2ns	2.8ns	2.8ns	3.0ns
t_{CO} (Register Clock to Out Time)	2.8ns	3.0ns	3.2ns	3.7ns
f_{MAX} (Maximum Operating Frequency)	300MHz	275MHz	250MHz	250MHz
Functional Gates	75K	150K	225K	300K
I/Os	141	149/193/253	193/317	317/381
Packages	256 fpBGA	208 PQFP 256 fpBGA 484 fpBGA	256 fpBGA 484 fpBGA	484 fpBGA 672 fpBGA

Cascading For Wide Operation

In several modes it is possible to cascade adjacent MFBs to support wider operation. Table 2 details the different cascading options. There are chains of MFBs in each device which determine those MFBs that are adjacent for the purposes of cascading. Table 3 indicates these chains. The ispXPLD 5000MX design tools automatically cascade blocks if required by a particular design.

Table 2. Cascading Modes For Wide Support

Mode	Cascading Function
Logic	**Input Width.** Allows two MFBs to act as a 136-input block.
	Arithmetic. Allow the carry chain to pass between two MFBs.
FIFO	**Memory Width Expansion.** Allows MFBs to be cascaded for greater width support.
CAM	**Memory Width Expansion.** Allows up to four MFBs to be cascaded for greater width support.

Table 3. MFB Cascade Chain

Device	MFBs in Cascade Chain
ispXPLD 5256MX	A → B → C → D
	H -> G -> F -> E
ispXPLD 5512MX	A → B → C → D → E → F → G → H
	P → O → N → M → L → K → J → I
ispXPLD 5768MX	D → C → B → A → X → W → V → U → T → S → R → Q
	E → F → G → H → I → J → K → L → M → N → O → P
ispXPLD 51024MX	H → G → F → E → D → C → B → A → AF → AE → AD → AC → AB → AA → Z → Y
	I → J → K → L → M → N → O → P → Q → R → S → T → U → V → W → X

SuperWIDE Logic Mode

In logic mode, each MFB contains 32 macrocells and a fully populated, programmable AND-array with 160 logic product terms and four control product terms. The MFB has 68 inputs from the Global Routing Pool, which are available in both true and complement form for every product term. It is also possible to cascade adjacent MFBs to create a block with 136 inputs. The four control product terms are used for shared reset, clock, clock enable, and output enable functions. Figure 3 shows the overall structure of the MFB in logic mode while Figure 4 provides a more detailed view from the perspective of a macrocell slice.

True Dual-Port SRAM Mode

In Dual-Port SRAM Mode the multi-function array is configured as a dual port SRAM. In this mode two independent read/write ports access the same 8,192-bits of memory. Data widths of 1, 2, 4, 8, and 16 are supported by the MFB. Figure 9 shows the block diagram of the dual port SRAM.

Write data, address, chip select and read/write signals are always synchronous (registered.) The output data signals can be synchronous or asynchronous. Resets are asynchronous. All inputs on the same port share the same clock, clock enable, and reset selections. All outputs on the same port share the same clock, clock enable, and reset selections. Selections may be made independently between both inputs and outputs and ports. Table 5 shows the possible sources for the clock, clock enable and initialization signals for the various registers.

Figure 9. Dual-Port SRAM Block Diagram

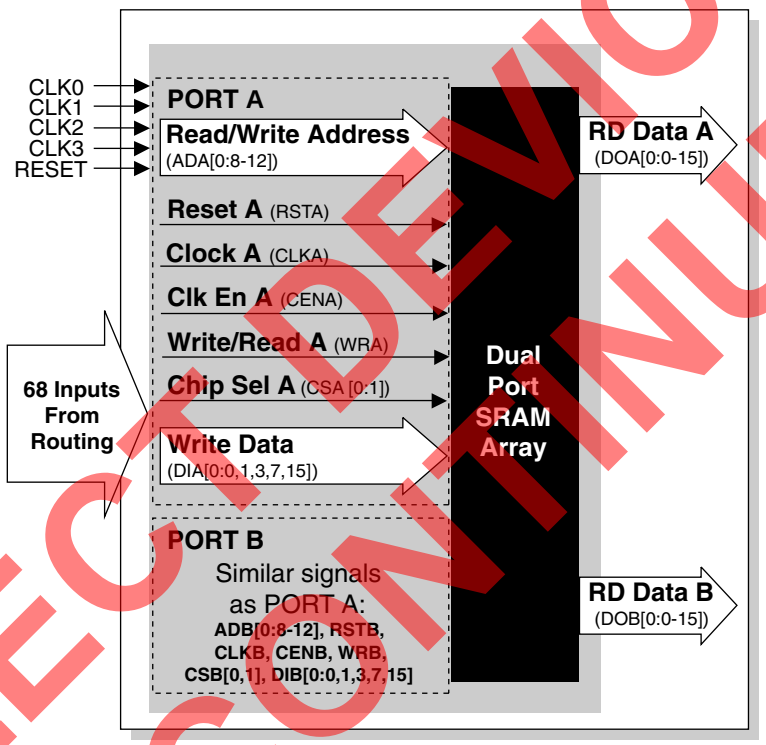

Table 5. Register Clock, Clock Enable, and Reset in Dual-Port SRAM Mode

Register	Input	Source
Address, Write Data, Read Data, Read/ Write, and Chip Select	Clock	CLKA (CLKB) or one of the global clocks (CLK0 - CLK3). The selected signal can be inverted if desired.
	Clock Enable	CENA (CENB) or one of the global clocks (CLK1 - CLK 2). The selected signal can be inverted if required.
	Reset	Created by the logical OR of the global reset signal and RSTA (RSTB). RSTA (RSTB) can be inverted is desired.

DC Electrical Characteristics

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{IL}, I_{IH}[1]	Input or I/O Leakage	0 ð V_{IN} ð (V_{CCO} - 0.2V)	—	—	10	µA
		(V_{CCO} - 0.2V) < V_{IN} ð 3.6V	—	—	40	µA
I_{IH}[4]	Input High Leakage Current	3.6V < V_{IN} ð 5.5V and 3.0V ð V_{CCO} ð 3.6V	—	—	3	mA
I_{PU}[3]	I/O Active Pullup Current	0 ð V_{IN} ð 0.7 V_{CCO}	-30	—	-150	µA
I_{PD}	I/O Active Pulldown Current	V_{IL} (MAX) ð V_{IN} ð V_{IH} (MAX)	30	—	150	µA
I_{BHLS}	Bus Hold Low Sustaining Current	V_{IN} = V_{IL} (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High Sustaining Current	V_{IN} = 0.7 V_{CCO}	30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive Current	0 ð V_{IN} ð V_{IH} (MAX)	—	—	150	µA
I_{BHHO}	Bus Hold High Overdrive Current	0 ð V_{IN} ð V_{IH} (MAX)	—	—	150	µA
V_{BHT}	Bus Hold Trip Points	0 ð V_{IN} ð V_{IH} (MAX)	V_{CCO} * 0.35	—	V_{CCO} * 0.65	µA
C1	I/O Capacitance[2]	V_{CCO} = 3.3V, 2.5V, 1.8V	—	8	—	pf
		V_{CC} = 1.8V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C2	Clock Capacitance[2]	V_{CCO} = 3.3V, 2.5V, 1.8V	—	8	—	pf
		V_{CC} = 1.8V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C3	Global Input Capacitance[2]	V_{CCO} = 3.3V, 2.5V, 1.8V	—	8	—	pf
		V_{CC} = 1.8V, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tristated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. T_A 25°C, f=1.0MHz
3. I_{PU} on JTAG pins has a maximum of -175µA for 5512MX devices.
4. 5V tolerant inputs and I/Os should be placed in banks where 3.0V ð V_{CCO} ð 3.6V. The JTAG and sysCONFIG ports are not included for the 5V tolerant interface.

sysIO Recommended Operating Conditions

Standard	V_{CCO} (V)[2]			V_{REF} (V)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
LVCMOS 3.3	3.0	3.3	3.6	—	—	—
LVCMOS 2.5	2.3	2.5	2.7	—	—	—
LVCMOS 1.8[1]	1.65	1.8	1.95	—	—	—
LVTTL	3.0	3.3	3.6	—	—	—
PCI 3.3	3.0	3.3	3.6	—	—	—
AGP-1X	3.15	3.3	3.45	—	—	—
SSTL 2	2.3	2.5	2.7	1.15	1.25	1.35
SSTL 3	3.0	3.3	3.6	1.3	1.5	1.7
CTT 3.3	3.0	3.3	3.6	1.35	1.5	1.65
CTT 2.5	2.3	2.5	2.7	1.35	1.5	1.65
HSTL Class I	1.4	1.5	1.6	0.68	0.75	0.9
HSTL Class III	1.4	1.5	1.6	—	0.9	—
HSTL Class IV	1.4	1.5	1.6	—	0.9	—
GTL+	1.4	—	3.6	0.882	1.0	1.122
LVDS	2.3	2.5/3.3	3.6	—	—	—

1. Design tools default setting.
2. Inputs are independent of V_{CCO} setting. However, V_{CCO} must be set within the valid operating range for one of the supported standards.

sysIO Single Ended DC Electrical Characteristics

Over Recommended Operating Conditions

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max (V)	V_{OH} Min (V)	I_{OL}[2] (mA)	I_{OH}[2] (mA)
	Min (V)	Max (V)	Min (V)	Max (V)				
LVCMOS 3.3	-0.3	0.8	2.0	5.5	0.4	2.4	20, 16, 12, 8, 5.33, 4	-20, -16, -12, -8, -5.33, -4
					0.2	V_{CCO} - 0.2	0.1	-0.1
LVTTL	-0.3	0.8	2.0	5.5	0.4	2.4	4	-4
					0.2	V_{CCO} - 0.2	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	V_{CCO} - 0.4	16, 12, 8, 5.33, 4	-16, -12, -8, -5.33, -4
					0.2	V_{CCO} - 0.2	0.1	-0.1
LVCMOS 1.8[1, 3]	-0.3	0.68	1.07	3.6	0.4	V_{CCO} - 0.4	8	-8
LVCMOS 1.8[3]	-0.3	0.68	1.07	3.6	0.4	V_{CCO} -0.4	12, 5.33, 4	-12, -5.33, -4
					0.2	V_{CCO} - 0.2	0.1	-0.1
PCI 3.3[4]	-0.3	1.08	1.5	3.6	0.1 V_{CCO}	0.9 V_{CCO}	1.5	-0.5
AGP-1X[4]	-0.3	1.08	1.5	3.6	0.1 V_{CCO}	0.9 V_{CCO}	1.5	-0.5
SSTL3 class I	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.7	V_{CCO} - 1.1	8	-8
SSTL3 class II	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.5	V_{CCO} - 0.9	16	-16
SSTL2 class I	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.54	V_{CCO} - 0.62	7.6	-7.6
SSTL2 class II	-0.3	V_{REF} - 0.18	V_{REF} + 0.18	3.6	0.35	V_{CCO} - 0.43	15.2	-15.2
CTT 3.3	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	V_{REF} - 0.4	V_{REF} + 0.4	8	-8
CTT 2.5	-0.3	V_{REF} - 0.3	V_{REF} + 0.2	3.6	V_{REF} - 0.4	V_{REF} + 0.4	8	-8
HSTL class I	-0.3	V_{REF} - 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} - 0.4	8	-8
HSTL class III	-0.3	V_{REF} - 0.2	V_{REF} + 0.1	3.6	0.4	V_{CCO} - 0.4	24	-8
HSTL class IV	-0.3	V_{REF} - 0.3	V_{REF} + 0.1	3.6	0.4	V_{CCO} - 0.4	48	-8
GTL+	-0.3	V_{REF} - 0.2	V_{REF} + 0.2	3.6	0.6	n/a	36	n/a

1. Software default setting.
2. The average DC current drawn by I/Os between adjacent bank GND connections, or between the last GND in an I/O bank and the end of the I/O bank, as shown in the logic signals connection table, shall not exceed n*8mA. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.
3. For 1.8V devices (ispXPLD 5000MC) these specifications are V_{IL} = 0.35 * V_{CC} and V_{IH} = 0.65 * V_{CC}.
4. For 1.8V devices (ispXPLD 5000MC) these specifications are V_{IL} = 0.3 * V_{CC} * 3.3/1.8, V_{IH} = 0.5 * V_{CC} * 3.3/1.8.

ispXPLD 5000MX Family External Switching Characteristics (Continued)[1, 2, 3]

Over Recommended Operating Conditions

Parameter	Description	-4		-45		-5		-52		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
f_{MAX} (RAM)[5]	Clock Frequency to RAM in:											
	Single Port Mode	—	155	—	155	—	155	—	155	—	93	MHz
	Dual Port Mode	—	155	—	155	—	155	—	155	—	93	MHz
	Pseudo Dual Port Mode	—	180	—	180	—	160	—	160	—	106	MHz
f_{MAX} (FIFO)[5]	Clock Frequency to FIFO	—	225	—	220	—	210	—	210	—	132	MHz
t_{PWR_ON}	Power-on Time	—	200	—	200	—	200	—	200	—	200	µs

Timing v.1.8

1. Timing numbers are based on default LVCMOS 1.8 I/O buffers. Use timing adjusters provided to calculate timing for other standards.
2. Measured using standard switching circuit, global routing loading of 1, worst case PTSA loading and 1 output switching.
3. Pulse widths and clock widths less than minimum will cause unknown behavior.
4. Standard 16-bit counter using GRP feedback.
5. CAM, FIFO, RAM f_{MAX} specification used shared PT Clk.

ispXPLD 5000MX Family Timing Adders (Continued)

Parameter	Description	Base Param.	-4		-45		-5		-52		-75		Units
			Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
HSTL_I_out	Using HSTL 2.5V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
HSTL_III_out	Using HSTL 2.5V, Class III	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
HSTL_IV_out	Using HSTL 2.5V, Class IV	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
LVDS_out	Using Low Voltage Differential Signaling (LVDS)	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.8	—	0.8	—	0.8	—	0.8	—	0.8	ns
LVPECL_out	Using Low Voltage PECL	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns
PCI_out	Using PCI Standard	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.6	—	0.6	—	0.6	—	0.6	—	0.6	ns
SSTL2_I_out	Using SSTL 2.5V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.3	—	0.3	—	0.3	—	0.3	—	0.3	ns
SSTL2_II_out	Using SSTL 2.5V, Class II	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.5	—	0.5	—	0.5	—	0.5	—	0.5	ns
SSTL3_I_out	Using SSTL 3.3V, Class I	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.2	—	0.2	—	0.2	—	0.2	—	0.2	ns
SSTL3_II_out	Using SSTL 3.3V, Class II	t_{IOBUF}, t_{IOEN}, t_{IODIS}	—	0.4	—	0.4	—	0.4	—	0.4	—	0.4	ns

Timing v.1.8

Signal Descriptions

Signal Names	Descriptions
TMS	Input – This pin is the Test Mode Select input, which is used to control the IEEE 1149.1 state machine.
TCK	Input – This pin is the Test Clock input pin, used to clock the IEEE 1149.1 state machine.
TDI	Input – This pin is the IEEE 1149.1 Test Data in pin, used to load data.
TDO	Output – This pin is the IEEE 1149.1 Test Data out pin used to shift data out.
TOE	Input – Test Output Enable pin. TOE tristates all I/O pins when driven low.
GOE0, GOE1	Input – Global output enable inputs.
RESET	Input – This pin resets all the registers in the device. The global polarity for this pin is selectable on a global basis.þ The default is active low. An external pull-down is required when polarity is set to active high.
yzz	Input/Output – These are the general purpose I/O used by the logic array. *y* is the MFB reference (alpha) and z is the macrocell reference (numeric) y: A-X (768 macrocells) y: A-P (512 macrocells) y: A-H (256 macrocells) z: 0-31
GND	GND – Ground
NC	No connect
V_{CC}	V_{CC} – The power supply pins for core logic.
V_{CCO0}, V_{CCO1}, V_{CCO2}, V_{CCO3}	V_{CC} – The power supply pins for I/O banks 0, 1, 2, and 3.
V_{REF0}, V_{REF1}, V_{REF2}, V_{REF3}	Input – This pin defines the reference voltage for I/O banks 0, 1, 2, and 3.
GCLK0, GCLK1, GCLK2, GCLK3	Input – Global clock/clock enable inputs (see Figure 14 for differential pairing).
CLK_OUT0, CLK_OUT1	Output – Optional clock output from PLL 0 and 1.
PLL_RST0, PLL_RST1	Input – Optional input resets the M divider in PLL 0 and 1.
PLL_FBK0, PLL_FBK1	Input – Optional feedback input for PLL 0 and 1.
GNDP	GND – Ground for PLLs.
V_{CCP}	V_{CC} – The power supply pin for PLLs.
V_{CCJ}	V_{CC} – The power supply for the IEEE 1149.1 interface.
DATA*x*	I/O – sysCONFIG data pins, bit *x*.
CSB	Input – sysCONFIG interface chip select. Drive low to select sysCONFIG interface.
CFG0	Input – Defines SRAM configuration mode. Low: sysCONFIG port, high: E^2CMOS or IEEE 1149.1 TAP.
PROGRAMB	Input – Controls the programming of SRAM. Hold high for normal operation. Toggle low to reload SRAM from E^2 memory.
CCLK[1]	Input – Clock for sysCONFIG interface. Reads and writes occur on the rising edge of the clock.
READ[1]	Input – Drive high to perform reads from the sysCONFIG interface.
INITB	I/O – Indicates status of configuration. Can be driven low to inhibit configuration.
DONE	Output (open drain) – Indicates status of configuration.

1. These inputs should not toggle during power up for proper power-up configuration.

ispXPLD 5512MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	208 PQFP Pin Number	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2				
1	13P	B24	A16	—	B25	—	T4	V6
—	—	V_{CCO1}	—	—	—	57	V_{CCO1}	V_{CCO1}
1	13N	B26	A18	—	B27	—	T5	V7
1	14P	B28	A20	—	B29	—	R4	Y5
1	14N	B30	A22	—	B31	—	N6	AA5
1	15P	C0	—	—	C1	—	R5	Y6
1	15N	C2	—	—	C3	—	P6	Y7
1	16P	C4	—	—	C5	—	—	AA6
1	16N	C8	—	—	C9	—	—	AA7
1	17P	C10	—	—	C11	—	—	W7
1	17N	C12	—	—	C13	—	M7[1]	V8
1	18P	C16	—	—	C17	—	T6	W8
1	18N	C18	—	—	C19	—	R6	U9
—	—	GND0 (Bank 1)	—	—	—	—	GND (Bank 1)	GND (Bank 1)
—	—	CFG0	—	—	—	58	L8	U10
—	—	V_{CCO1}	—	—	—	—	V_{CCO1}	V_{CCO1}
1	19P	C24	B16	D16	C25	59	T7	AB7
1	19N	C26	B17	D17	C27	60	R7	AA8
1	20P	C28	B18	D18	C29	61	N7	AB8
1	20N	D0	B19	D19	D1	62	P7	AB9
1	21P	D2	B20	D20	D3	63	T8	W9
1	21N	D4	B21	D21	D5	64	R8	Y9
1	22P	D6	B22	D22	D7	65	M8	AB10
1	22N	D8	B23	D23	D9	66	P8	AA10
1	—	D10/V_{REF1}	—	—	D11	67	L9	W10
1	23P	D12	B24	D24	D13	68	N8	Y10
1	23N	D16	B25	D25	D17	69	M9	Y11
—	—	GND (Bank 1)	—	—	—	70	GND (Bank 1)	GND (Bank 1)
1	24P	D18	B26	D26	D19	71	N10	V9
—	—	VCCO1	—	—	—	72	V_{CCO1}	V_{CCO1}
1	24N	D20	B27	D27	D21	73	T9	V10
1	25P	D22	B28	D28	D23	74	T10	AA11
1	25N	D24	B29	D29	D25	75	R9	AB11
—	—	VCC	—	—	—	76	VCC	VCC
1	26P	D26	B30	D30	D27	77	P9	U11
1	26N	D28	B31	D31	D29	78	N9	V11
2	27P	E0	F0	H0	E1	79	T11	AB12
2	27N	E2	F1	H1	E3	80	T12	AA12
—	—	GND	—	—	—	81	NC	GND
—	—	GND	—	—	—	—	GND	GND
2	28P	E4	F2	H2	E5	82	P10	Y12
2	28N	E6	F3	H3	E7	83	R10	AA13
2	29P	E8	F4	H4	E9	84	R11	V12

ispXPLD 5512MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Input	208 PQFP Pin Number	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2				
3	79N	K8	K5	L8	K9	—	—	F13
3	79P	K6	K4	L6	K7	—	—	F15
3	80N	K5	K3	L5	—	—	—	D16
3	80P	K4	K2	L4	—	—	E10[1]	E16
3	81N	K2	K1	L2	K3	—	A12	A16
3	81P	K0	K0	L0	K1	—	A11	A15
—	—	GND (Bank 3)	—	—	—	—	GND (Bank 3)	GND (Bank 3)
3	82N	L30	I15	K15	L31	162	B11	B15
—	—	V_{CCO3}	—	—	—	—	V_{CCO3}	V_{CCO3}
3	82P	L28	I14	K14	L29	163	C11	A14
3	83N	L26	I13	K13	L27	164	B10	D15
3	83P	L24	I12	K12	L25	165	A10	E15
3	84N	L22	I11	K11	L23	166	C10	D14
3	84P	L21	I10	K10	—	167	D10	F14
3	85N	L20	I9	K9	—	168	C9	A13
3	85P	L18	I8	K8	L19	169	E9	B13
3	86N	L16/VREF3	I29	K29	L17	170	D9	C14
3	86P	L14	I28	K28	L15	171	F9	E14
3	87N	L12	I7	K7	L13	172	A9	E13
3	87P	L10	I6	K6	L11	173	F8	F12
—	—	GND (Bank 3)	—	—	—	174	GND (Bank 3)	GND (Bank 3)
3	88N	L8	I5	K5	L9	175	E8	D13
—	—	V_{CCO3}	—	—	—	176	V_{CCO3}	V_{CCO3}
3	88P	L6	I4	K4	L7	177	A8	C13
3	89N	L5	I3	K3	—	178	B9	E12
3	89P	L4	I2	K2	—	179	D8	C12
—	—	VCC	—	—	—	180	VCC	VCC
3	90N	L2	I1	K1	L3	181	B8	B12
3	90P	L0	I0	K0	L1	182	C8	A12
0	91N	M30	M31	O31	M31	183	B7	E11
0	91P	M28	M30	O30	M29	184	A7	C11
—	—	GND	—	—	—	185	—	GND
—	—	GND	—	—	—	—	GND	GND
0	92N	M26	M29	O29	M27	186	D7	B11
0	92P	M24	M28	O28	M25	187	C7	A11
0	93N	M22	M27	O27	M23	188	B6	F11
—	—	V_{CCO0}	—	—	—	189	V_{CCO0}	V_{CCO0}
0	93P	M21	M26	O26	M22	190	E7	F10
—	—	GND (Bank 0)	—	—	—	191	GND (Bank 0)	GND (Bank 0)
0	94N	M20	M25	O25	M21	192	E6	E10
0	94P	M18	M24	O24	M19	193	A6	C10
0	95N	M16/V_{REF0}	M3	O3	M17	194	A5	D10
0	95P	M14	M2	O2	M15	195	A4	B10

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
2	46N	G6	H19	-	G7	—	AB19
2	47P	G8	H20	-	G9	—	AA19
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	47N	G10	H21	-	G11	—	U17
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	48P	G12	H22	-	G13	—	V18
2	48N	G14	H23	-	G15	—	AB21
2	49P	G16	H24	-	G17	—	U18
2	49N	G18	H25	-	G19	—	T17
2	50P	G20	H26	-	G21	R16	AB20
2	50N	G22	H27	-	G23	P16	AA20
2	51P	G24	H28	-	G25	N15	Y19
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	51N	G26	H29	-	G27	N14	V19
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	52P	G28	F16	H16	G29	N16	T18
2	52N	G30	F17	H17	G31	M16	R17
2	53P	H0	F18	H18	H1	M14	U19
2	53N	H2	F19	H19	H3	M15	T19
2	54P	H4	H30	E24	H5	—	V20
-	-	VCC	-	-	-	VCC	VCC
2	54N	H6	H31	E26	H7	—	U20
2	55P	H8	F20	H20	H9	L13	W20
2	55N	H10	F21	H21	H11	L12	Y21
2	56P	H12	F22	H22	H13	L15	R18
2	56N	H14	F23	H23	H15	L16	R19
-	-	GND	-	-	-	GND	GND
2	57P	H16	F24	H24	H17	L14	W21
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	57N	H18	F25	H25	H19	K15	Y22
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	58P	H20	F26	H26	H21	K14	R20
2	58N	H22	F27	H27	H23	K12	P20
2	59P	H24	F28	H28	H25	K13	T21
2	59N	H26	F29	H29	H27	J13	R21
2	60P	H28	F30	H30	H29	J14	U21
2	60N	H30	F31	H31	H31	J12	V21
-	-	TOE	-	-	-	J15	W22
-	-	RESET	-	-	-	J11	V22
-	-	GOE0	-	-	-	H11	T22
-	-	GOE1	-	-	-	H13	R22
-	-	GNDP	-	-	-	See Power Supply and NC Connections Table	

ispXPLD 5768MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/ Function	Alternate Outputs		Alternate Inputs	256 fpBGA Ball Number	484 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	GCLK3N	GCLK2	-	-	-	H15	P16
-	-	VCCP	-	-	-	See Power Supply and NC Connections Table	
-	GCLK3P	GCLK3	-	-	-	H16	N16
3	61N	J0	L31	J31	-	H14	J22
3	61P	J2	L30	J30	J3	G16	H22
3	62N	J4	L29	J29	J5	—	N19
3	62P	J6	L28	J28	J7	—	P15
3	63N	J8	L27	J27	J9	—	P21
3	63P	J10	L26	J26	J11	—	N15
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	64N	J12	L25	J25	J13	—	M15
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	64P	J14	L24	J24	J15	—	N20
-	-	GND	-	-	-	GND	GND
3	65N	J16	L23	J23	J17	—	P22
3	65P	J18	L22	J22	J19	—	N21
3	66N	J20	L21	J21	J21	—	N17
3	66P	J22	L20	J20	J23	—	M20
3	67N	J24	L19	J19	J25	—	P17
-	-	VCC	-	-	-	VCC	VCC
3	67P	J26	L18	J18	J27	—	P18
3	68N	J28	L17	J17	J29	—	M21
3	68P	J30	L16	J16	J31	—	M17
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	69N	L0	L15	J15	-	—	L20
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	69P	L2	L14	J14	L3	—	N18
3	70N	L4	L13	J13	L5	—	L21
3	70P	L6	L12	J12	L7	—	M18
3	71N	L8	L11	J11	L9	—	L22
3	71P	L10	L10	J10	L11	—	L17
3	72N	L12	L9	J9	L13	—	K22
3	72P	L14	L8	J8	L15	—	L18
3	73N	L16	L7	J7	L17	—	K21
3	73P	L18	L6	J6	L19	—	K18
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	74N	L20	L5	J5	L21	—	K20
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	74P	L22	L4	J4	L23	—	K17
3	75N	L24	L3	J3	L25	—	K19
3	75P	L26	L2	J2	L27	—	J17
3	76N	L28	L1	J1	L29	G15	E22

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	-	GND	-	-	-	GND	GND
2	46P	I4	J2	L2	I5	Y12	AF19
2	46N	I6	J3	L3	I7	AA13	AF20
2	47P	I8	J4	L4	I9	V12	AF21
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	47N	I10	J5	L5	I11	U12	AF22
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	48P	I12	J6	L6	I13	AB13	AF23
2	48N	I14	J7	L7	I15	Y13	AF24
2	49P	I16	L0	-	I17	V13	AE17
2	49N	I18/VREF2	L1	-	I19	W13	AE18
2	50P	I20	J8	L8	I21	V14	AE19
2	50N	I22	J9	L9	I23	W14	AE20
2	51P	I24	J10	L10	I25	Y14	AE21
2	51N	I26	J11	L11	I27	AB14	AE22
2	52P	I28	J12	L12	I29	AB15	AE23
2	52N	I30	J13	L13	I31	AA15	AE24
2	53P	J0	J14	L14	J1	U13	AD17
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	53N	J2	J15	L15	J3	U14	AD18
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	54P	J4	L2	I0	J5	W15	AD19
2	54N	J6	L3	I2	J7	W16	AD20
2	55P	J8	L4	I4	J9	Y16	AD21
2	55N	J10	L5	I6	J11	AA16	AD22
2	56P	J12	L6	I8	J13	AB16	AD23
2	56N	J14	L7	I10	J15	AA17	AD24
2	57P	J16	L8	I12	J17	Y17	AC22
2	57N	J18	L9	I16	J19	AA18	AC21
2	58P	J20	L10	I20	J21	W17	AC18
-	-	VCC	-	-	-	VCC	VCC
2	58N	J22	L11	I22	J23	W18	AC19
-	-	GND	-	-	-	GND	GND
2	59P	J24	L12	-	J25	V15	AC20
-	-	VCCO2		-	-	VCCO2	VCCO2
2	59N	J26	L13	-	J27	U15	AB21
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	60P	J28	L14	-	J29	Y18	AB18
2	60N	J30	L15	-	J31	V17	AB19
2	61P	K0	L16	-	K1	V16	AB20
2	61N	K2	L17	-	K3	U16	AA20
2	62P	K4	L18	-	K5	AB18	AA19
2	62N	K6	L19	-	K7	AB19	Y19

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
2	63P	K8	L20	-	K9	AA19	AA18
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	63N	K10	L21	-	K11	U17	Y18
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	64P	K12	L22	-	K13	V18	AD25
2	64N	K14	L23	-	K15	AB21	AD26
2	65P	K16	L24	-	K17	U18	AC23
2	65N	K18	L25	-	K19	T17	AC24
2	66P	K20	L26	-	K21	AB20	AC25
2	66N	K22	L27	-	K23	AA20	AC26
2	67P	K24	L28	-	K25	Y19	AB22
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	67N	K26	L29	-	K27	V19	AB23
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	68P	K28	J16	L16	K29	T18	AB24
2	68N	K30	J17	L17	K31	R17	AB25
2	69P	L0	J18	L18	L1	U19	AB26
2	69N	L2	J19	L19	L3	T19	AA26
2	70P	L4	L30	I24	L5	V20	AA22
-	-	VCC	-	-	-	VCC	VCC
2	70N	L6	L31	I26	L7	U20	Y21
2	71P	L8	J20	L20	L9	W20	AA23
2	71N	L10	J21	L21	L11	Y21	AA24
2	72P	L12	J22	L22	L13	R18	AA25
2	72N	L14	J23	L23	L15	R19	Y26
-	-	GND	-	-	-	GND	GND
2	73P	L16	J24	L24	L17	W21	Y22
-	-	VCCO2	-	-	-	VCCO2	VCCO2
2	73N	L18	J25	L25	L19	Y22	Y23
-	-	GND (Bank 2)	-	-	-	GND (Bank 2)	GND (Bank 2)
2	74P	L20	J26	L26	L21	R20	W20
2	74N	L22	J27	L27	L23	P20	V20
2	75P	L24	J28	L28	L25	T21	W21
2	75N	L26	J29	L29	L27	R21	V21
2	76P	L28	J30	L30	L29	U21	Y24
2	76N	L30	J31	L31	L31	V21	Y25
2	77P	N0	P0	N0	N1	—	W22
2	77N	N2	P1	N1	N3	—	W23
2	78P	N4	P2	N2	N5	—	W24
-	-	VCC	-	-	-	VCC	VCC
2	78N	N6	P3	N3	N7	—	W25
-	-	GND	-	-	-	GND	GND
2	79P	N8	P4	N4	N9	—	W26

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	110N	U4	X25	V25	U5	H21	J21
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	110P	U6	X24	V24	U7	G21	H21
-	-	GND	-	-	-	GND	GND
3	111N	U8	X23	V23	U9	D22	G25
3	111P	U10	X22	V22	U11	D21	G24
3	112N	U12	X21	V21	U13	J20	G23
3	112P	U14/CLK_OUT1	X20	V20	U15	J19	G22
3	113N	U16	V31	-	U17	E20	J20
-	-	VCC	-	-	-	VCC	VCC
3	113P	U18	V30	U30	U19	F20	H20
3	114N	U20	V29	U28	U21	H17	G26
3	114P	U22	V28	U26	U23	H18	F25
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	115N	U24	V27	-	U25	J18	F24
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	115P	U26	V26	-	U27	H19	F23
3	116N	U28	V25	-	U29	G20	G21
3	116P	U30	V24	-	U31	G19	F22
-	-	GND	-	-	-	GND	GND
3	117N	V0	V23	-	V1	C22	F26
-	-	VCC	-	-	-	VCC	VCC
3	117P	V2	V22	-	V3	C21	E26
3	118N	V4	V21	-	V5	D20	E25
3	118P	V6	V20	-	V7	C19	E24
3	119N	V8	V19	-	V9	F19	E23
3	119P	V10	V18	-	V11	E19	E22
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)
3	120N	V12	V17	-	V13	G18	D26
-	-	VCCO3	-	-	-	VCCO3	VCCO3
3	120P	V14	V16	-	V15	F18	D25
3	121N	V16	V15	-	V17	B20	D24
3	121P	V18	V14	-	V19	B19	D23
3	122N	V20	V13	-	V21	A20	C26
3	122P	V22	V12	-	V23	A19	C25
3	123N	V24	X19	V19	V25	D18	G19
3	123P	V26	X18	V18	V27	C18	F19
3	124N	V28	X17	V17	V29	G17	G18
3	124P	V30	X16	V16	V31	F16	F18
3	125N	W0	X31	V31	W1	E17	F20
3	125P	W2	X30	V30	W3	D17	E20
-	-	GND (Bank 3)	-	-	-	GND (Bank 3)	GND (Bank 3)

ispXPLD 51024MX Logic Signal Connections (Continued)

sysIO Bank	LVDS Pair	Primary Macrocell/Function	Alternate Outputs		Alternate Input	484 fpBGA Ball Number	672 fpBGA Ball Number
			Macrocell 1	Macrocell 2			
0	142N	Y26	Y29	AA29	Y27	B11	A10
0	142P	Y24	Y28	AA28	Y25	A11	A9
0	143N	Y22	Y27	AA27	Y23	F11	A8
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	143P	Y20	Y26	AA26	Y21	F10	A7
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	144N	Y18	Y25	AA25	Y19	E10	A6
0	144P	Y16	Y24	AA24	Y17	C10	A5
0	145N	Y14/VREF0	Y3	AA3	Y15	D10	A4
0	145P	Y12	Y2	AA2	Y13	B10	A3
0	146N	Y10	Y23	AA23	Y11	A10	B10
0	146P	Y8	Y22	AA22	Y9	A9	B9
0	147N	Y6	Y21	AA21	Y7	C9	B8
0	147P	Y4	Y20	AA20	Y5	D9	B7
0	148N	Y2	Y19	AA19	Y3	F9	B6
0	148P	Y0	Y18	AA18	Y1	E9	B5
0	149N	Z30	Y1	AA1	Z31	A8	B4
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	149P	Z28	Y0	AA0	Z29	B8	B3
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	150N	Z26	AA29	-	Z27	A7	C10
0	150P	Z24	AA28	-	Z25	B7	C9
0	151N	Z22	AA27	-	Z23	A5	C8
0	151P	Z20	AA26	-	Z21	B5	C7
0	152N	Z18	AA25	-	Z19	B6	C6
0	152P	Z16	AA24	-	Z17	C7	C5
0	153N	Z14	AA23	-	Z15	E8	C4
0	153P	Z12	AA22	-	Z13	E7	D5
0	154N	Z10	AA21	-	Z11	E6	D9
-	-	VCC	-	-	-	VCC	VCC
0	154P	Z8	AA20	-	Z9	D6	D8
-	-	GND	-	-	-	GND	GND
0	155N	Z6	AA19	-	Z7	D8	D7
-	-	VCCO0	-	-	-	VCCO0	VCCO0
0	155P	Z4	AA18	-	Z5	F8	D6
-	-	GND (Bank 0)	-	-	-	GND (Bank 0)	GND (Bank 0)
0	156N	Z2	AA17	-	Z3	F7	F9
0	156P	Z0	AA16	-	Z1	D7	E9
0	157N	AA30	AA15	-	AA31	C6	F7
0	157P	AA28	AA14	-	AA29	C5	F8
0	158N	AA26	AA13	-	AA27	C4	G8
0	158P	AA24	AA12	-	AA25	D5	G9

ispXPLD 5000MB (2.5V) Lead-Free Commercial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MB	LC5256MB-4FN256C	256	2.5	4.0	Lead-free fpBGA	256	141	C
	LC5256MB-5FN256C	256	2.5	5.0	Lead-free fpBGA	256	141	C
	LC5256MB-75FN256C	256	2.5	7.5	Lead-free fpBGA	256	141	C
LC5512MB	LC5512MB-45QN208C	512	2.5	4.5	Lead-free PQFP	208	149	C
	LC5512MB-75QN208C	512	2.5	7.5	Lead-free PQFP	208	149	C
	LC5512MB-45FN256C	512	2.5	4.5	Lead-free fpBGA	256	193	C
	LC5512MB-75FN256C	512	2.5	7.5	Lead-free fpBGA	256	193	C
	LC5512MB-45FN484C	512	2.5	4.5	Lead-free fpBGA	484	253	C
	LC5512MB-75FN484C	512	2.5	7.5	Lead-free fpBGA	484	253	C
LC5768MB	LC5768MB-5FN256C	768	2.5	5.0	Lead-free fpBGA	256	193	C
	LC5768MB-75FN256C	768	2.5	7.5	Lead-free fpBGA	256	193	C
	LC5768MB-5FN484C	768	2.5	5.0	Lead-free fpBGA	484	317	C
	LC5768MB-75FN484C	768	2.5	7.5	Lead-free fpBGA	484	317	C
LC51024MB	LC51024MB-52FN484C	1024	2.5	5.2	Lead-free fpBGA	484	317	C
	LC51024MB-75FN484C	1024	2.5	7.5	Lead-free fpBGA	484	317	C
	LC51024MB-52FN672C	1024	2.5	5.2	Lead-free fpBGA	672	381	C
	LC51024MB-75FN672C	1024	2.5	7.5	Lead-free fpBGA	672	381	C

ispXPLD 5000MB (2.5V) Lead-Free Industrial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MB	LC5256MB-5FN256I	256	2.5	5.0	Lead-free fpBGA	256	141	I
	LC5256MB-75FN256I	256	2.5	7.5	Lead-free fpBGA	256	141	I
LC5512MB	LC5512MB-75QN208I	512	2.5	7.5	Lead-free PQFP	208	149	I
	LC5512MB-75FN256I	512	2.5	7.5	Lead-free fpBGA	256	193	I
	LC5512MB-75FN484I	512	2.5	7.5	Lead-free fpBGA	484	253	I
LC5768MB	LC5768MB-75FN256I	768	2.5	7.5	Lead-free fpBGA	256	193	I
	LC5768MB-75FN484I	768	2.5	7.5	Lead-free fpBGA	484	317	I
LC51024MB	LC51024MB-75FN484I	1024	2.5	7.5	Lead-free fpBGA	484	317	I
	LC51024MB-75FN672I	1024	2.5	7.5	Lead-free fpBGA	672	381	I

ispXPLD 5000MV (3.3V) Lead-Free Commercial Devices

Device	Part Number	Macrocells	Voltage (V)	t_{PD} (ns)	Package	Pin/Ball Count	I/O	Grade
LC5256MV	LC5256MV-4FN256C	256	3.3	4.0	Lead-free fpBGA	256	141	C
	LC5256MV-5FN256C	256	3.3	5.0	Lead-free fpBGA	256	141	C
	LC5256MV-75FN256C	256	3.3	7.5	Lead-free fpBGA	256	141	C

Revision History

Date	Version	Change Summary
—	—	Previous Lattice releases.
December 2003	07	Added ispXPLD 5768MX information (supply current, timings, power consumption, power estimation coefficients, memory coefficients, logic signal connections, ordering part numbers).
		Updated ispXPLD 5000MX timing numbers (version v.1.7).
		Added lead-free package designator.
		Removed ispXPLD 5000MC industrial temperature grade ordering part numbers.
January 2004	08	Lead-free package release for the ispXPLD 5000MC and 5000MV devices.
		Timing model parameter tCOi correction - Maximum specification instead of Minimum (no changes in the timing numbers).
March 2004	08.1	Updated the MFB Cascade Chain table for the ispXPLD 5256MX device.
May 2004	09	Updated the ispXPLD 5000MX timig numbers (version v.1.8) ispXPLD 5256MC, 5512MC and 51024MC industrial temperature grade devices release
		Updated typical supply current data and condition.
		ispXPLD 5256MX 256-fpBGA logic signal connection tables: Removed internal signal description for ball H5 and G14.
August 2004	10	Added footnote "1, page 49. These inputs should not toggle during power up for proper power-up configuration." to CCLK and READ.
		Added ispXPLD 5768MC Industrial grade OPNs (Conventional and Lead-Free).
October 2004	10.1	Figure 19, LVPECL Driver with Three Resistor Pack has been updated (ispXPLD LVPECL Buffer changed to ispXPLD Emulated LVPECL Buffer)
November 2004	11	Added ispXPLD 5000MB (2.5V) Lead-Free Ordering Part Numbers.
December 2004	11.1	Pin name RESETB has been updated to RESET.
March 2005	12	208-PQFP Lead-free package release for the ispXPLD 5512MV/B/C devices.
April 2005	12.1	Page 23, clarification of footnote regarding IDK specification.
March 2006	12.2	Signal description for RESET has been updated.
April 2009	12.3	Ordering Information section has been updated to describe alternate LC5768MB/MV top side marking format.
February 2010	12.4	References to "system gates" changed to "functional gates."